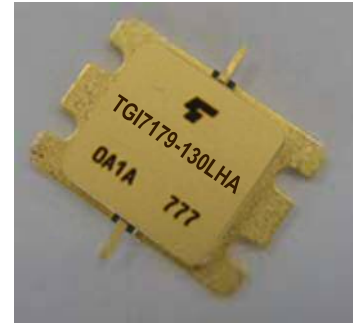


FEATURES

- **BROAD BAND INTERNALLY MATCHED HEMT**
- **HIGH POWER**
Pout= 51.0dBm at Pin= 43.5dBm
- **HIGH GAIN**
GL= 12.0dB at Pin= 20dBm
- **LOW INTERMODULATION DISTORTION WITH WIDE SPACING TONE**
IM3= -25dBc(Min.) at Pout= 44dBm (Single Carrier Level)
- **HERMETICALLY SEALED PACKAGE**



RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power	Pout	VDS= 40V IDSset= 0.8A f= 7.1 to 7.9GHz @Pin= 43.5dBm	dBm	50.0	51.0	—
Drain Current	IDS1		A	—	7.0	9.0
Power Added Efficiency	η_{add}		%	—	36	—
Linear Gain	GL	@Pin= 20dBm	dB	11.0	12.0	—
Gain flatness	ΔG		dB	—	—	± 0.8
3rd Order Intermodulation Distortion	IM3	Two-Tone Test Po= 44dBm (Single Carrier Level) Δf = 5MHz (IM3) Δf = 150MHz (IM3-2)	dBc	-25	-30	—
	IM3-2		dBc	-25	-27	—
Drain Current	IDS2		A	—	—	5.0
Channel Temperature Rise *1	ΔT_{ch}		°C	—	120	140

Recommended Gate Resistance(Rg): 10 Ω

*1: $\Delta T_{ch} = (VDS \times IDS2 + Pin(two-tone) - Po(two-tone)) \times Rth(c-c)$, calculated using parameters of IM3 test

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

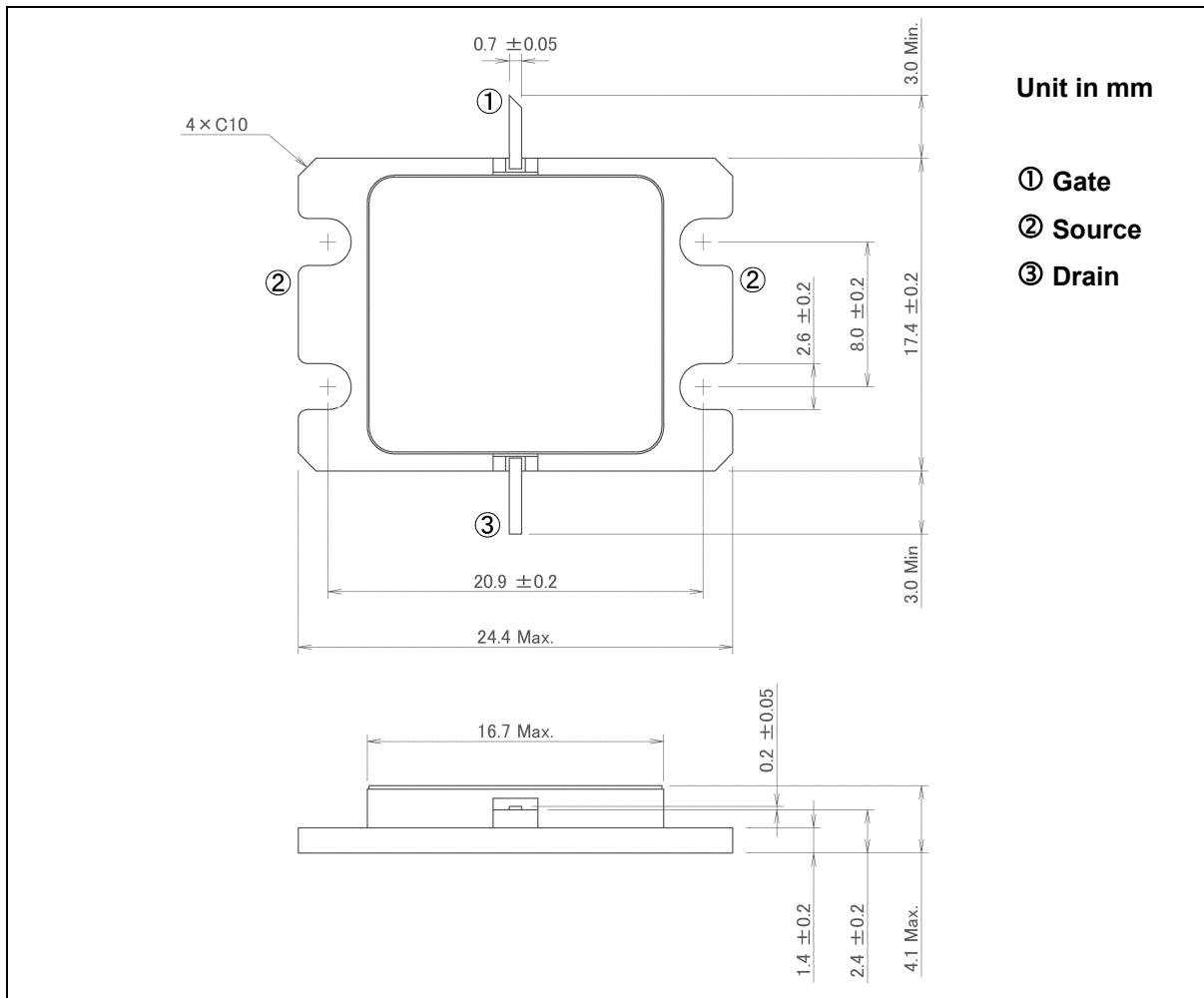
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 5V IDS= 10.0A	S	—	8.0	—
Pinch-off Voltage	VGSoff	VDS= 5V IDS= 30mA	V	-2.0	-3.0	-5.0
Saturated Drain Current	IDSS	VDS= 5V VGS= 0V	A	—	20	—
Gate-Source Breakdown Voltage	VGSO	IGS= -25mA	V	-10	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	0.8	1.0

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ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	50
Gate-Source Voltage	VGS	V	-10
Drain Current	IDS	A	12
Total Power Dissipation (Tc= 25°C)	PT	W	200
Channel Temperature	Tch	°C	225
Storage Temperature	Tstg	°C	-65 to +175

PACKAGE OUTLINE (7-AA06A)



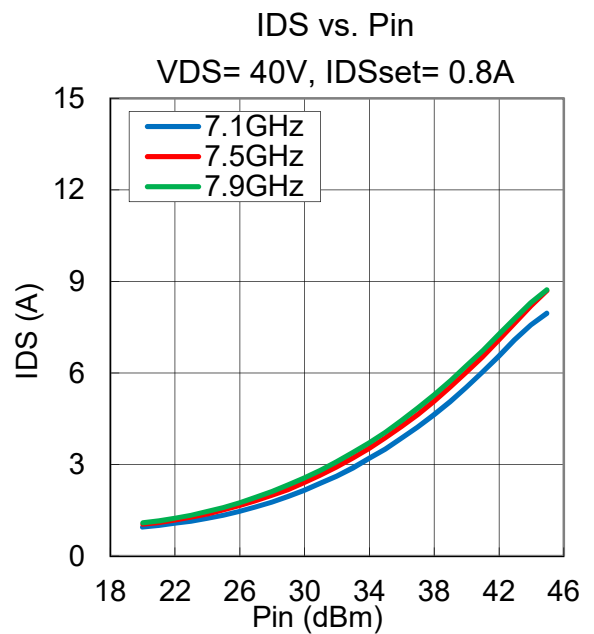
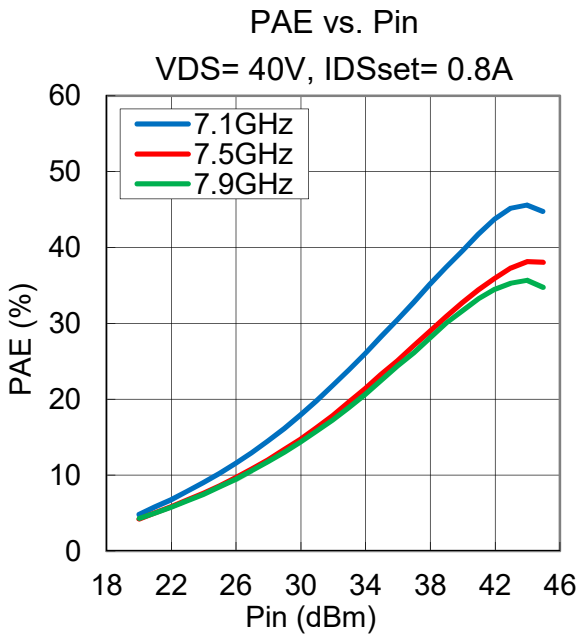
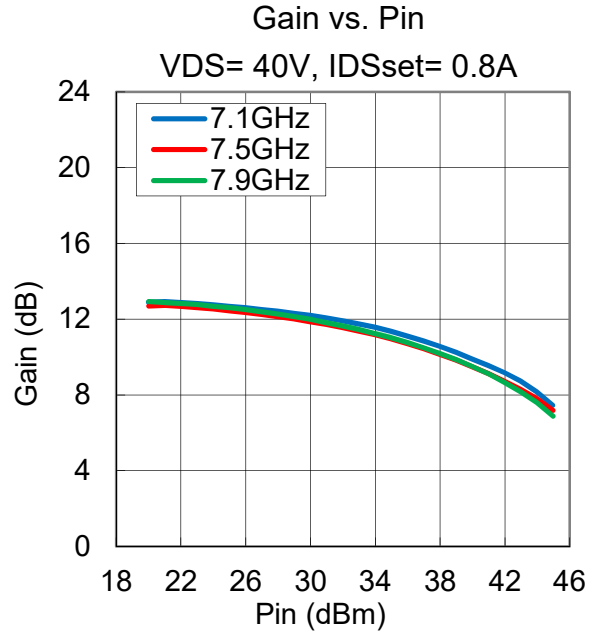
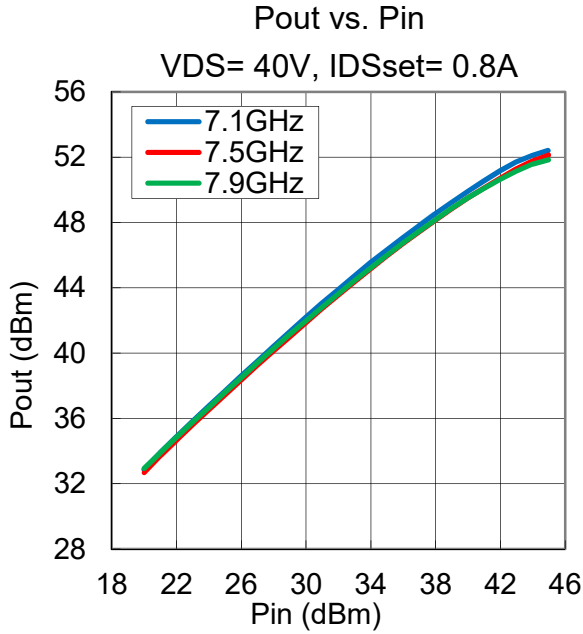
HANDLING PRECAUTIONS FOR PACKAGE MODEL

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C or 3 seconds at 350°C.

TYPICAL RF PERFORMANCE

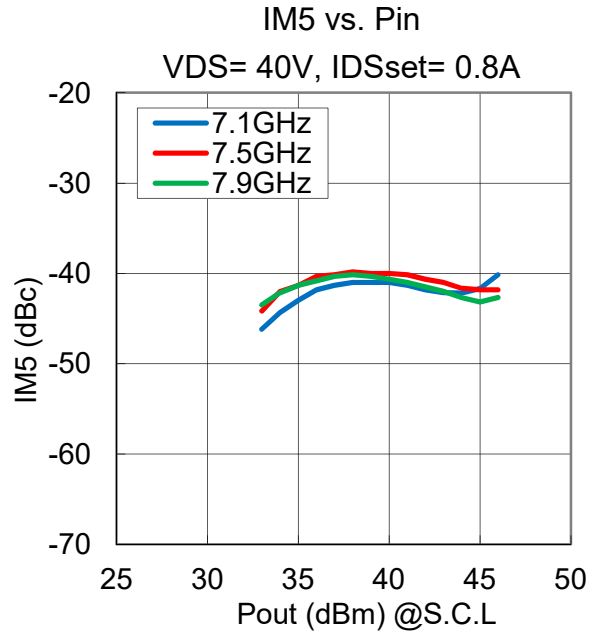
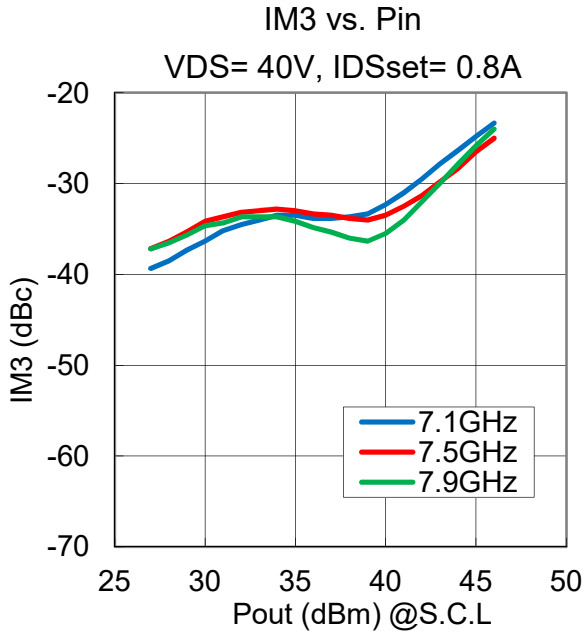
• Pout, Gain, PAE, IDS vs. Pin

VDS= 40V, IDSset= 0.8A, f= 7.1, 7.5, 7.9GHz, Ta= +25°C



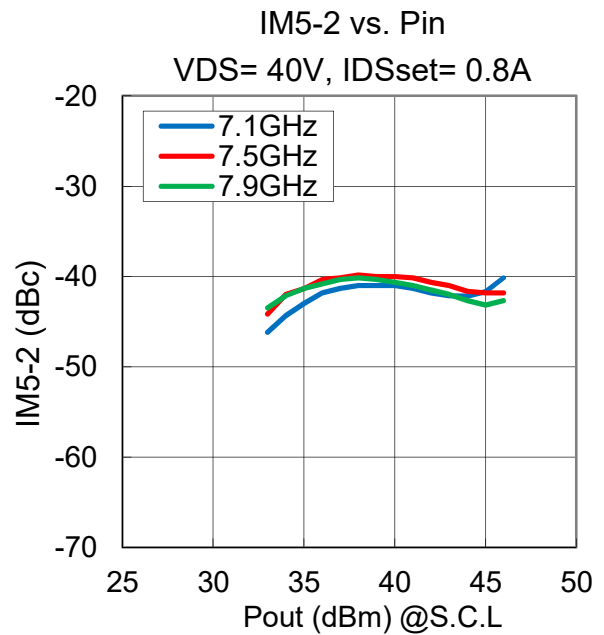
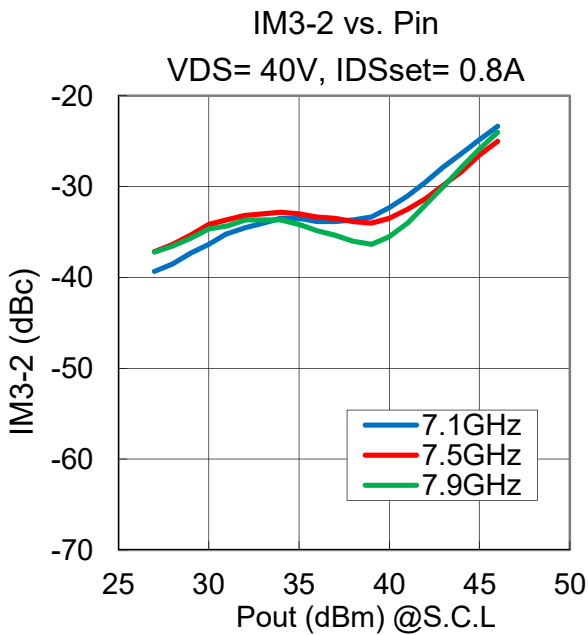
•IM3, IM5 vs Pout

VDS= 40V, IDSset= 0.8A, f= 7.1, 7.5, 7.9GHz, Δf= 5MHz, Ta= +25°C



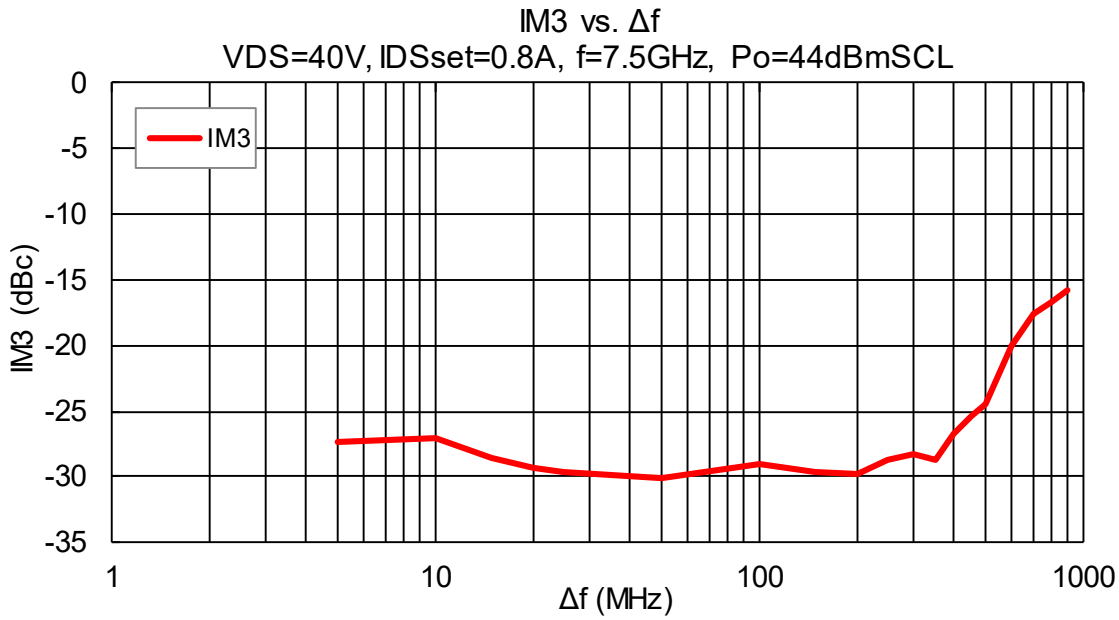
•IM3-2, IM5-2 vs Pout

VDS= 40V, IDSset= 0.8A, f= 7.1, 7.5, 7.9GHz, Δf= 150MHz, Ta= +25°C



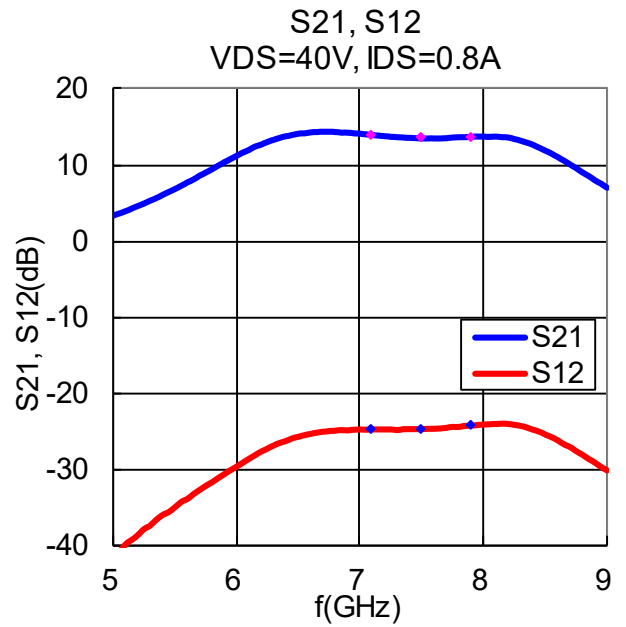
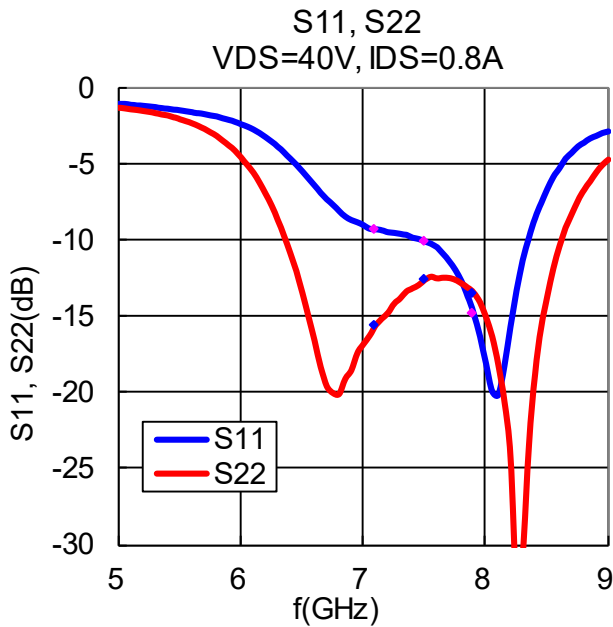
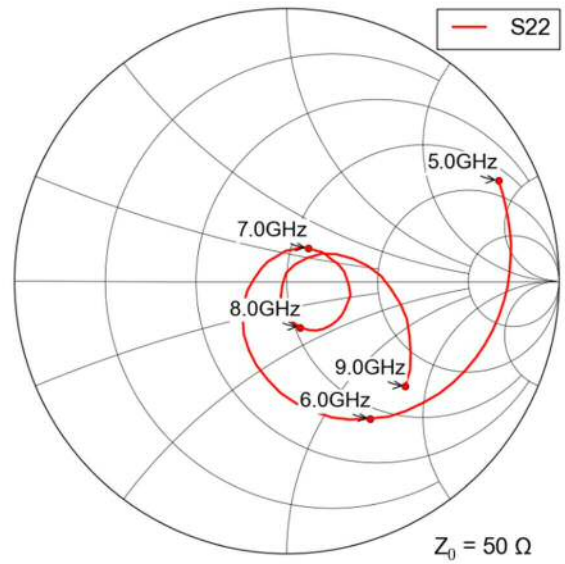
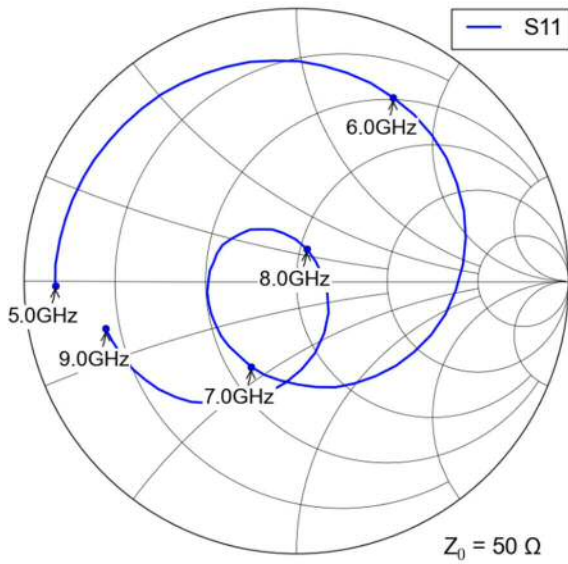
·IM3 vs. Δf (Two tone spacing)

VDS= 40V, IDSset= 0.8A, f= 7.5GHz, Po= 44dBmSCL, Ta= +25°C



-S-Parameters

VDS= 40 V, IDSset= 0.8 A, f= 5.0 to 9.0 GHz, Ta= +25 °C



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